MOSFET - N-Channel Shielded Gate PowerTrench®

150 V, 7.3 mΩ, 101 A

NTP7D3N15MC

Features

- Shielded Gate MOSFET Technology
- Max $R_{DS(on)} = 7.3 \text{ m}\Omega$ at $V_{GS} = 10 \text{ V}$, $I_D = 62 \text{ A}$
- 50% Lower Qrr than other MOSFET Suppliers
- Lowers Switching Noise/EMI
- 100% UIL Tested
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Typical Applications

- Synchronous Rectification for ATX / Server / Telecom PSU
- Motor Drives and Uninterruptible Power Supplies
- Micro Solar Inverter

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V _{DSS}	150	V
Gate-to-Source Voltage	9		V _{GS}	±20	V
Continuous Drain Current R _{θJC} (Note 2)	Steady State		I _D	101	Α
Power Dissipation $R_{\theta JC}$ (Note 2)	Oldic		P _D	166	W
Continuous Drain Current $R_{\theta JA}$ (Notes 1, 2)	Steady State	T _Δ = 25°C	I _D	12.1	Α
Power Dissipation R _{θJA} (Notes 1, 2)	State		P _D	2.4	W
Pulsed Drain Current	T _C = 25°	C, t _p = 100 μs	I _{DM}	574	Α
Operating Junction and Range	T _J , T _{stg}	-55 to +175	°C		
Single Pulse Drain-to-Source Avalanche Energy (I _L = 20 A _{pk} , L = 3 mH)			E _{AS}	600	mJ
Lead Temperature for S (1/8" from case for 10 s)	TL	260	°C		

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

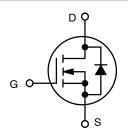
- 1. Surface-mounted on FR4 board using a 1 in², 2 oz. Cu pad.
- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.



ON Semiconductor®

www.onsemi.com

V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX
150 V	7.3 mΩ @ 10 V	101 A



N-CHANNEL MOSFET

MARKING

TO-220 CASE 221A TO-3 3 TO-220 Source

NTP7D3N15MC = Specific Device Code

A = Assembly Location

Y = Year WW = Work Week ZZ = Lot Traceability

ORDERING INFORMATION

Device	Package	Shipping [†]
NTP7D3N15MC	TO-220 (Pb-Free)	800 / Tube

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State (Note 2)	$R_{ hetaJC}$	0.9	°C/W
Junction-to-Ambient - Steady State (Note 2)	$R_{ hetaJA}$	62.5	

ELECTRICAL CHARACTERISTICS (T_{.1} = 25°C unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS					•	•	•
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		150			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /	I _D = 250 μA, ref	to 25°C		71		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V, V _{DS} = 120 V	T _J = 25°C			1.0	μΑ
Gate-to-Source Leakage Current	I _{GSS}	$V_{DS} = 0 V, V_{GS}$	= ±20 V			±100	nA
ON CHARACTERISTICS							
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D =$: 342 μA	2.5		4.5	V
Negative Threshold Temperature Coefficient	V _{GS(TH)} /T _J	I _D = 342 μA, ref	to 25°C		-7.3		mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 10 V, I _D	= 62 A		6.2	7.3	
		V _{GS} = 8 V, I _D	= 31 A		6.6	8.4	mΩ
Forward Transconductance	9FS	V _{DS} = 10 V, I _D	= 62 A		119		S
CHARGES, CAPACITANCES & GATE RESIS	TANCE					•	
Input Capacitance	C _{ISS}			4250			
Output Capacitance	C _{OSS}	V _{GS} = 0 V, f = 1 MHz	z, V _{DS} = 75 V		1250		рF
Reverse Transfer Capacitance	C _{RSS}			15		1	
Gate-Resistance	R_{G}				0.8	1.6	Ω
Total Gate Charge	Q _{G(TOT)}			53		nC	
Threshold Gate Charge	Q _{G(TH)}	V _{GS} = 10 V, V _{DS} = 75 V; I _D = 62 A			14		
Gate-to-Source Charge	Q _{GS}				23		
Gate-to-Drain Charge	Q_{GD}				8.5		
Plateau Voltage	V _{GP}				5.8		V
Output Charge	Q _{OSS}	V _{DD} = 75 V, V _{GS} = 0 V			133		nC
SWITCHING CHARACTERISTICS (Note 3)						•	•
Turn-On Delay Time	t _{d(ON)}				27		
Rise Time	t _r	VGS = 10 V. VDF	s = 75 V.		8.5		1
Turn-Off Delay Time	t _{d(OFF)}	V_{GS} = 10 V, V_{DD} = 75 V, I_{D} = 62 A, R_{G} = 4.7 Ω			33		ns ns
Fall Time	t _f				5.8		
DRAIN-SOURCE DIODE CHARACTERISTIC	s						
Forward Diode Voltage	V _{SD}	V _{GS} = 0 V, I _S = 62 A	T _J = 25°C		0.93	1.2	V
Reverse Recovery Time	t _{RR}	V _{GS} = 0 V, V _{DD}	= 75 V		55		ns
Reverse Recovery Charge	Q _{RR}	$dI_S/dt = 300 A/\mu s$,			247		nC
Reverse Recovery Time	t _{RR}	V _{GS} = 0 V, V _{DD}	= 75 V		50		ns
Reverse Recovery Charge	Q _{RR}	$d_{S}/dt = 1000 \text{ A/}\mu\text{s}, I_{S} = 62 \text{ A}$			720		nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS

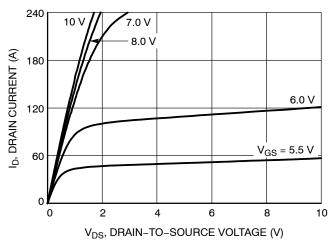


Figure 1. On-Region Characteristics

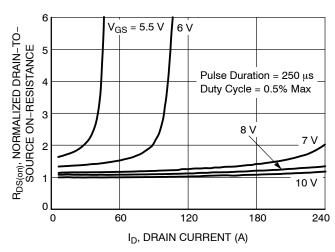


Figure 2. Normalized On–Resistance vs. Drain Current and Gate Voltage

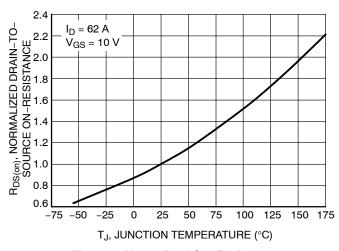


Figure 3. Normalized On–Resistance vs. Junction Temperature

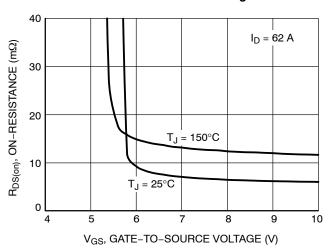


Figure 4. On-Resistance vs. Gate-to-Source Voltage

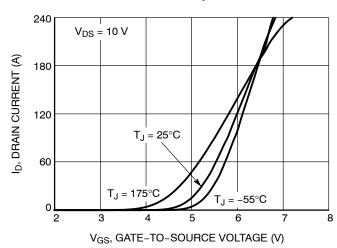


Figure 5. Transfer Characteristics

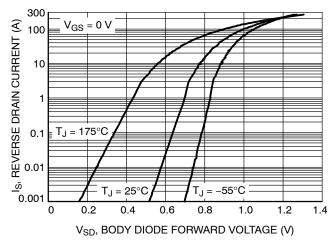


Figure 6. Source-to-Drain Diode Forward Voltage vs. Source Current

TYPICAL CHARACTERISTICS

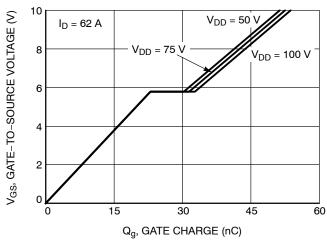


Figure 7. Gate Charge Characteristics

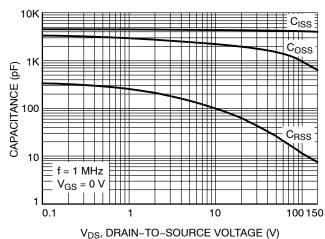


Figure 8. Capacitance vs. Drain-to-Source
Voltage

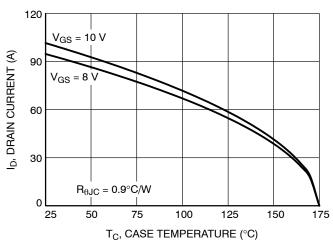


Figure 9. Drain Current vs. Case Temperature

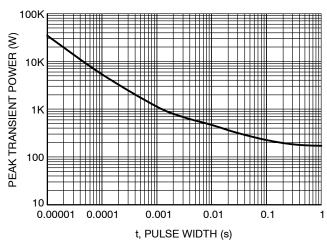


Figure 10. Peak Power

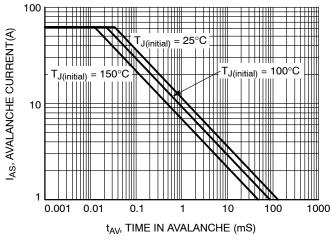


Figure 11. Unclamped Inductive Switching Capability

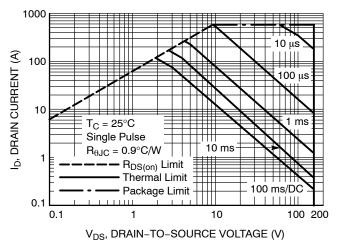


Figure 12. Forward Bias Safe Operating Area

TYPICAL CHARACTERISTICS

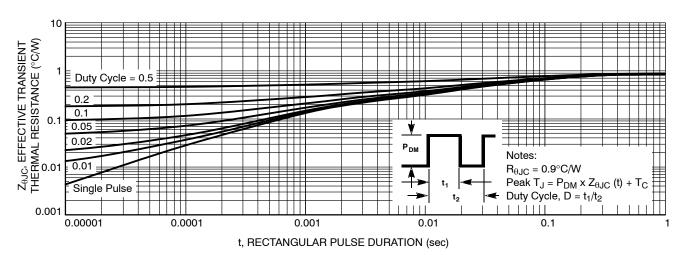
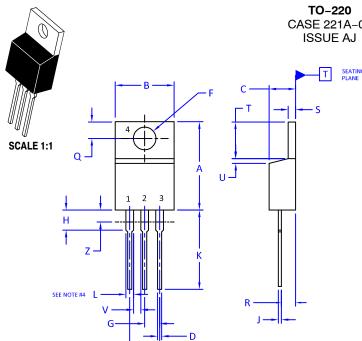


Figure 13. Transient Thermal Impedance

MECHANICAL CASE OUTLINE



CASE 221A-09

DATE 05 NOV 2019

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 2009.
- 2. CONTROLLING DIMENSION: INCHES
- 3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

4. MAX WIDTH FOR F102 DEVICE = 1.35MM

	INCH	HES	MILLIMETERS		
DIM	MIN.	MAX.	MIN.	MAX.	
Α	0.570	0.620	14.48	15.75	
В	0.380	0.415	9.66	10.53	
С	0.160	0.190	4.07	4.83	
D	0.025	0.038	0.64	0.96	
F	0.142	0.161	3.60	4.09	
G	0.095	0.105	2.42	2.66	
Н	0.110	0.161	2.80	4.10	
J	0.014	0.024	0.36	0.61	
К	0.500	0.562	12.70	14.27	
L	0.045	0.060	1.15	1.52	
N	0.190	0.210	4.83	5.33	
Q	0.100	0.120	2.54	3.04	
R	0.080	0.110	2.04	2.79	
S	0.045	0.055	1.15	1.41	
Т	0.235	0.255	5.97	6.47	
U	0.000	0.050	0.00	1.27	
V	0.045		1.15		
Z		0.080		2.04	

STYLE 1:		STYLE 2:		STYLE 3:		STYLE 4:	
PIN 1.	BASE	PIN 1.	BASE	PIN 1.	CATHODE	PIN 1.	MAIN TERMINAL 1
2.	COLLECTOR	2.	EMITTER	2.	ANODE	2.	MAIN TERMINAL 2
3.	EMITTER	3.	COLLECTOR	3.	GATE	3.	GATE
4.	COLLECTOR	4.	EMITTER	4.	ANODE	4.	MAIN TERMINAL 2
STYLE 5:		STYLE 6:		STYLE 7:		STYLE 8:	
PIN 1.	GATE	PIN 1.	ANODE	PIN 1.	CATHODE	PIN 1.	CATHODE
2.	DRAIN	2.	CATHODE	2.	ANODE	2.	ANODE
3.	SOURCE	3.	ANODE	3.	CATHODE	3.	EXTERNAL TRIP/DELAY
4.	DRAIN	4.	CATHODE	4.	ANODE	4.	ANODE
STYLE 9:		STYLE 10:		STYLE 11	:	STYLE 12	:
PIN 1.	GATE	PIN 1.	GATE	PIN 1.	DRAIN	PIN 1.	MAIN TERMINAL 1
2.	COLLECTOR	2.	SOURCE	2.	SOURCE	2.	MAIN TERMINAL 2
3.	EMITTER	3.	DRAIN	3.	GATE	3.	GATE
4.	COLLECTOR	4.	SOURCE	4.	SOURCE	4.	NOT CONNECTED

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